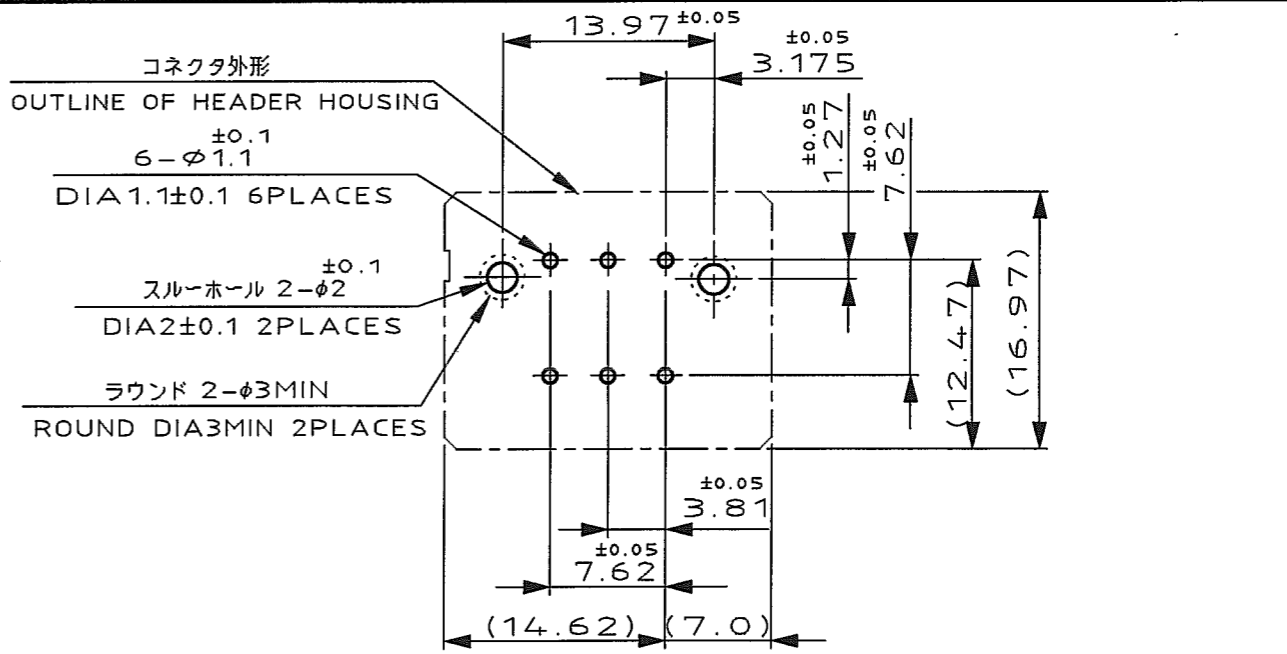
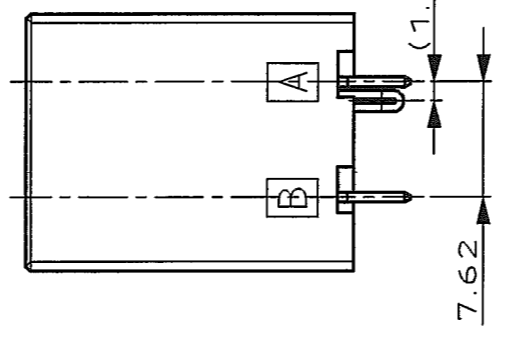
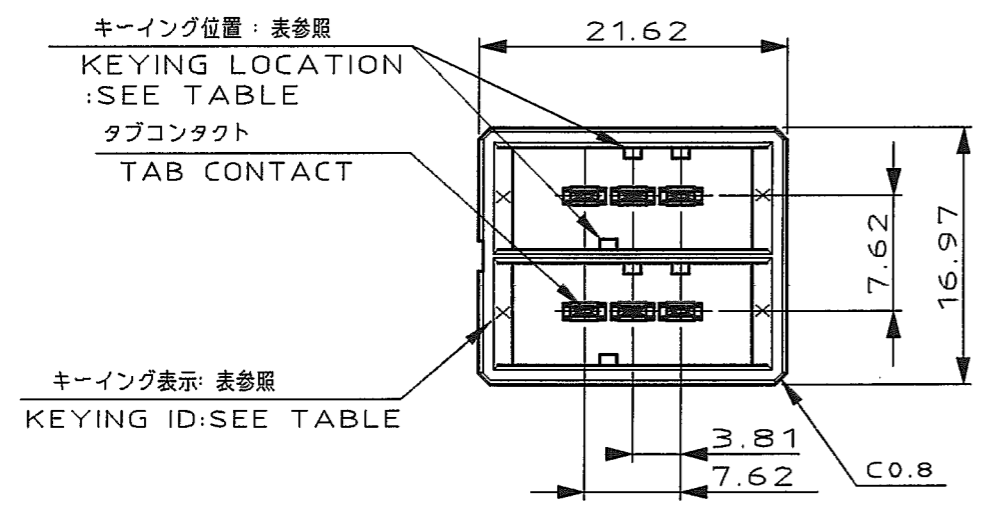


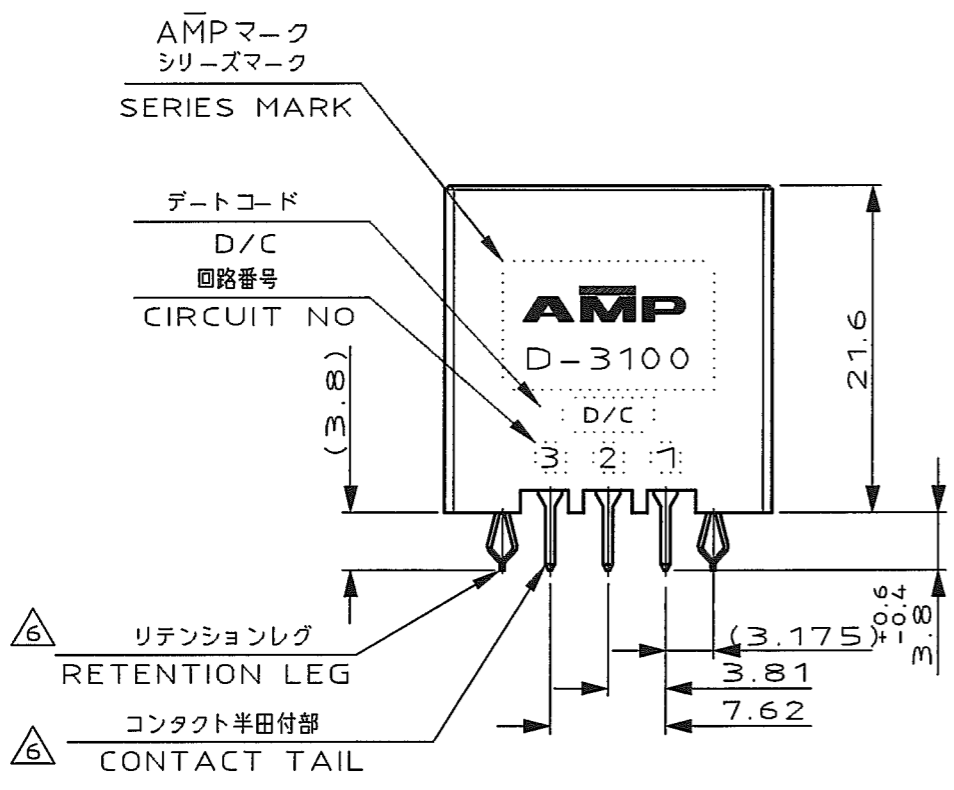
NUMBER 178141
METRIC

PRINT DIST
DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT



推奨基板取付け穴寸法
PC 基板厚: 1.6 ±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6 ±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
コネクタ: 銅合金
リテンションレグ: 銅合金
- めっき: コネクタ: 全面Ni下地
接触部: 0.38 μm MIN 金めっき
- めっき: コネクタ: 全面Ni下地
接触部: 0.76 μm MIN 金めっき
- めっき: コネクタ: 全面Ni下地
接触部: 2.0 μm MIN スズめっき
- めっき: リテンションレグとコネクタ半田付部
ニッケル下地の上に半田めっき
- めっき: リテンションレグとコネクタ半田付部
ニッケル下地の上にスズめっき

A ROW		X	Y	△6	△4	3-178141-5	
B ROW				△6	△3	3-178141-3	
A ROW		X	X	△6	△4	1-178141-5	
B ROW				△6	△3	1-178141-3	
				△6	△2	1-178141-2	
KEYING LOCATION				A ROW KEYING	B ROW KEYING	FINISH	製品番号 PART NO.



WIRE RANGE	INSULATION DIA	NAME	DYNAMIC D-3100 3.81X7.62 PITCH (V) 6 POS. HDR CONN. ASS'Y			
mm (AWG)	mmφ		一般公差 (GENERAL TOLERANCE)	SIZE	LOC	NUMBER
SEE NOTE 注記参照	SEE NOTE 注記参照		100% ±0.3 100% 300% ±0.4 300% 100% ±0.45 角度 ±3'	A3	J	178141
DR. 19 APR 94 N. Matsubara	DE. 19 APR 94 N. Matsubara	SCALE	REV.	SHEET		
CHK. 20 APR 94 S. MANABE	APP. 20 APR 94 S. MANABE	2-1	E1	1 OF 1		

E1	REVISED PER ECO-11-005030	RK	HMR	28MAR 11
LTR	REVISION RECORD	DR	CHK	DATE